Complete Texturing/Cleaning/Etching Metrology



QualiSurf® PV Control Your Chemical Process

When you select In-process analysis equipment for a critical manufacturing step, you need confidence in your results and follow-up actions.

ECI's expertise and unparalleled experience combining multi-disciplinary analytical techniques for accurate and efficient in-process analysis is the reason for our proven leadership.

Texturing and other wet solutions are constantly changing. Analysis by Titration or other wet methods is accurate but time consuming and requires expensive reagents. Non-reagent Spectroscopic techniques can be used to control the process much more efficiently with no



cost per analysis. However, Texturing, Cleaning and Etch processes use highly concentrated solutions and generate particles and byproducts known to interfere with spectral analysis. By using the most advanced spectroscopic cell design on the market, combined with ECI's automated validation module, the system provides the most stable and accurate real-time measurement of your Texturing bath.

Before QualiSurf PV, thousands of wafers would be manufactured under uncertain conditions between lab analyses. With QualiSurf PV, you can be confident that your Texturing bath stays within your specifications.

In-line Metrology for Wet Processes Texturing, Single-Side Edge Isolation, Si Etch, PSG Removal





We Keep The Chemistry Right.

QualiSurf PV

A real time analyzer for Photovoltaic Texturing, Etching and Cleaning - Measuring **Concentrations and Process Performance**

Features and Benefits

- Reports individual concentrations and by-products in multiple-component chemistries, reflectivity, and etch rate
- Superior accuracy and reproducibility
- Innovative cell design for fluctuating texturing conditions
- Automated validation and calibration
- Safe enclosure with easy process tool connection
- Feedback signals for automatic closed loop control of process equipment
- Supports multiple baths
- Minimal PM requirements
- Fast and easy startup

Typical Applications

Texturing

Stop Log Ce

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- --Isotropic Acid Etch:
 - HF/HNO3/H2SiF6
 - HF/HNO3/H2SO4/H2SiF6
 - HF/HNO3/Organic Acid/ H2SiF6

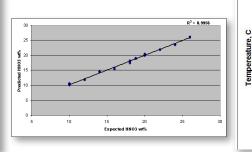
--Anisotropic Alkaline Etch:

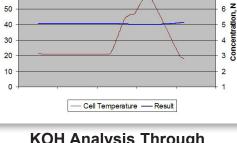
- NaoH/Na2SiO3
- KOH/K2SiO3
- KOH/IPA/K2SiO3
- KOH/Organic Acid/K2SiO3

- **PSG Glass Etch** - HF/H2SiF6
 - Edge Isolation - HF/HNO3/H2SiF6
 - Clean - HF, HF/HCI, KOH

HNO . 5/28 6/2 6/7

Typical Texturing Solution Analysis





HNO₃ Calibration Curve

KOH Analysis Through **Temperature Changes**

ECI can develop analyses for customers' proprietary applications. Backed by ECI Global Support



File Satup Report Tools Holp

Etch

Clean

HF

5.47 wt% -0.04 22.69 °C 1009 6:20 28 8

ниоз

35.5 wt% 0.7 9.20 °C 2009 6 20 28 PM

Texturing Solution Analysis

Main Screen

Si

30.0 of

HCI

10.520 wt% +0.102 22.69*C (2009.6.20.28 Pt

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Note: H2SiF6, Na2SiO3, and K2SiO3 are reaction products and not added into a fresh bath.

70 60

50

- NaOH/IPA/Na2SiO3